

# PCN97009A Data

## Thermal Data for Thermally Enhanced Plastic Quad Flat Pack (PQFP)

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### Still Air Data Comparison:

	<b>HQFP (Current Non-Insulated)</b>	<b>HQFP (Insulated)</b>	<b>PQFP (Std)</b>
	JA (°C/watt)	JA (°C/watt)	JA (°C/watt)
<b>208 pins</b>	14 - 15	14 - 16	25 - 32
<b>240 pins</b>	11 - 14	11 - 15	18 - 28

### Notes:

JC Data:

1. HQFP (Thermally Enhanced) = 0.7 - 1.2°C/watt, typical.  
PQFP (Standard PQFP) = 2.0 - 7.0°C/watt, typical.
2. Test Conditions per JEDEC JC15.1.
3. Data measured using a 4-layer test board.
4. Used Delco Thermal Die. Die sizes vary, compatible to Xilinx device sizes.